Product Change Notification: MFOL-01VBNG552

Date:

07-Oct-2025

Product Category:

Memory

Notification Subject:

CCB 7877.002 Final Notice: Qualification of EFTEC-64T as a new leadframe material and 558-2C31 as a new die attach material for 24CW320T-I/MUY, 24CW160T-I/MUY, 24CW1280T-I/MUY, and 24CW640T-I/MUY catalog part numbers (CPN) available in 8L UDFN (2x3x0.5mm) package at NSEB assembly site.

Affected CPNs:

MFOL-01VBNG552_Affected_CPN_10072025.pdf
MFOL-01VBNG552_Affected_CPN_10072025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of EFTEC-64T as a new leadframe material and 558-2C31 as a new die attach material for 24CW320T-I/MUY, 24CW160T-I/MUY, 24CW1280T-I/MUY, and 24CW640T-I/MUY catalog part numbers (CPN) available in 8L UDFN (2x3x0.5mm) package at NSEB assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-1) LTD. (NSEB)
Wire Material	Au	Au

Die Attach Material	8200T (PFAS)	558-2C31 (PFAS-free)
Molding Compound Material	G700LTD	G700LTD
Lead-Frame Material	C7025	EFTEC-64T
Lead-Frame DAP Surface Prep	NiPdAu	Bare copper (Ag on lead only)

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying EFTEC-64T as a new leadframe material and 558-2C31 as a new die attach to standardize the use of PFAS free material.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 October 2025 (date code: 2544)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2025				
Work Week	40	41	42	43	44
Qual Report Availability		X			
Final PCN Issue Date		X			
Estimated Implementation Date					X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: October 7, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-01VBNG552_Pre and Post Change_Summary.pdf
PCN_MFOL-01VBNG552_Qualification_Reports.pdf
PFAS Elimination and Die Attach_Explanation.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.